[install label in silkscreened box after final wash. Text shall be 0 pt font. Text shall be per the Label Table in the PDF schematic.]

[These assemblies are ESD sensitive, ESD precautions shall be observed.]

[These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.]

[These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.]

[Place SH3 onto J3 Pin 1 - 2]
[Place SH5 onto J5 Pin 1 - 2]
[Place SH8 onto J8 Pin 1 - 2]
[Place SH1 onto J1 Pin 2 - 3]
[Place SH2 onto J2 Pin 1 - 2]
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